

Advance Announcement

The Institute of Electrical and Electronics Engineers, Inc.
Components, Packaging and Manufacturing Technology Society
Orange County Chapter



Presents an All-Day Workshop on

3D Integrated Circuits: Technologies Enabling the Revolution

Date: **Friday, December 9, 2011**
Time: **9:00 am to 4:00pm**
Location: **Jazz Semiconductor Auditorium, 4311 Jamboree Road, Newport Beach, CA 92660**

This one-day topical workshop will provide a comprehensive examination of the technologies, materials, manufacturing processes, equipment, test methodology, and design tools that are enabling three-dimensional integrated circuits (3DICs). Join us at this unique event that brings together experts in all of the above areas to discuss the promise of 3D Integration.

Featured Speakers

Dr. Phil Garrou

Microelectronic Consultants of North Carolina

Dr. Muhannad Bakir,

Georgia Tech – Integrated 3D Systems Group

Ted Tessier,

Chief Technical Officer, Flip Chip International

Dr. Suresh Ramalingam

Sr. Director, Adv. Pkg Design & Development, Xilinx

Rose Guino, Betty Huang, Kevin Becker

Henkel Corporation

Dr. Yeong Lee,

Director, STATS ChipPAC

...and many others.

Registration Details at http://meetings.vtools.ieee.org/meeting_view/list_meeting/8019. For more information please contact

General Information & Sponsorship:

Dr. Lawrence Williams at l.williams@ieee.org

Vendor Exhibition:

Mark Kuhlman at Mkuhlman@semtech.com

IEEE CPMT OC Chapter Website: <http://sites.ieee.org/ocs-cpmpt>

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ECTC 2012

May 29 - June 1, 2012
Sheraton San Diego Hotel & Marina
San Diego, California, USA

The 62nd Electronic Components and Technology Conference

The 62nd ECTC Call for Papers is now open!

The Electronic Components and Technology Conference (ECTC) invites you to submit an abstract for presentations and/or Professional Development Courses (4 hours). As the premier event in the semiconductor assembly industry, ECTC addresses new developments, trends and applications in integrated systems packaging.

We welcome previously unpublished, non-commercial abstracts in areas including, but not limited to:

- Advanced Packaging
- Applied Reliability
- Assembly & Manufacturing Technology
- Electronic Components & RF
- Emerging Technologies
- Interconnections
- Materials & Processing
- Modeling & Simulation
- Optoelectronics

Abstract submissions and Professional Development Course proposals for the 62nd ECTC are due by **October 10, 2011**.
To submit, visit:
www.ectc.net

Conference Sponsors: